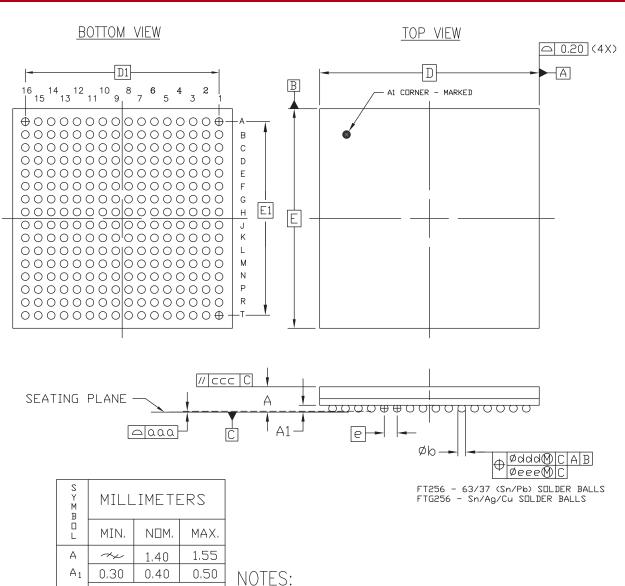


## 256 Ball Fine-Pitch Thin BGA (FT256/FTG256) Package





## D/E 17.00 BSC $\mathbb{D}_1/\mathbb{E}_1$ 15,00 REF 1.00 BSC 6 Øb 0.40 0.50 0.60 aaa 0.20 N X 0.15 CCC X 4 0.25 ddd eee N X 0.10 М 16

- 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
- 2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
- 3. CONFORMS TO JEDEC MS-034 AAF-1 EXCEPT FOR THE SOLDER BALL SIZE.

PK053\_01\_021511

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/23/05	1.2.1	Update.
10/05/07	1.3	Changed the A1 minimum dimension to 0.30 mm.
03/23/11	1.4	Changed the FTG256 solder ball description.

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